

## High voltage power Schottky rectifier

### Main product characteristics

$I_{F(AV)}$	2 x 7.5 A
$V_{RRM}$	100 V
$T_j$ (max)	175° C
$V_F$ (max)	0.67 V

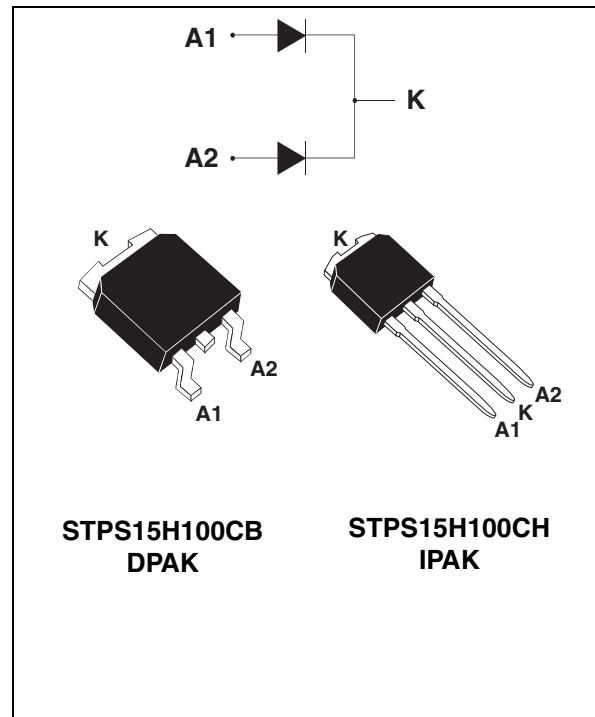
### Features and Benefits

- Negligible switching losses
- Low leakage current
- Good trade off between leakage current and forward voltage drop
- Low thermal resistance
- Avalanche capability specified

### Description

Dual center tab Schottky rectifier suited for switched mode power supply and high frequency DC to DC converters.

Packaged in DPAK and IPAK, this device is intended for use in high frequency inverters.



**Table 1. Absolute Ratings (limiting values, per diode)**

Symbol	Parameter	Value	Unit	
$V_{RRM}$	Repetitive peak reverse voltage	100	V	
$I_{F(RMS)}$	RMS forward current	10	A	
$I_{F(AV)}$	Average forward current	$T_c = 135^\circ\text{C}$ Per diode	7.5	A
		$\delta = 0.5$ Per device	15	
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms sinusoidal}$	75	A
$I_{RRM}$	Peak repetitive reverse current	$t_p = 2\ \mu\text{s square F} = 1\ \text{kHz}$	1	A
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 1\ \mu\text{s } T_j = 25^\circ\text{C}$	6600	W
$T_{stg}$	Storage temperature range	-65 to + 175	°C	
$T_j$	Maximum operating junction temperature <sup>(1)</sup>	175	°C	
dV/dt	Critical rate of rise of reverse voltage	10000	V/ $\mu\text{s}$	

1.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

# 1 Characteristics

**Table 2. Thermal resistance**

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	4	°C/W
		Total	2.4	
$R_{th(c)}$	Coupling		0.7	

When the diodes 1 and 2 are used simultaneously :

$$\Delta T_j(\text{diode 1}) = P(\text{diode1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

**Table 3. Static electrical characteristics (per diode)**

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ \text{C}$	$V_R = V_{RRM}$			3	$\mu\text{A}$
		$T_j = 125^\circ \text{C}$			1.3	4	mA
$V_F^{(1)}$	Forward voltage drop	$T_j = 25^\circ \text{C}$	$I_F = 7.5 \text{ A}$			0.8	V
		$T_j = 125^\circ \text{C}$	$I_F = 7.5 \text{ A}$		0.62	0.67	
		$T_j = 25^\circ \text{C}$	$I_F = 12 \text{ A}$			0.85	
		$T_j = 125^\circ \text{C}$	$I_F = 12 \text{ A}$		0.68	0.73	
		$T_j = 25^\circ \text{C}$	$I_F = 15 \text{ A}$			0.89	
		$T_j = 125^\circ \text{C}$	$I_F = 15 \text{ A}$		0.71	0.76	

1. Pulse test:  $t_p = 380 \mu\text{s}$ ,  $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.58 \times I_{F(AV)} + 0.012 I_{F(RMS)}^2$$

Figure 1. Conduction losses versus average current

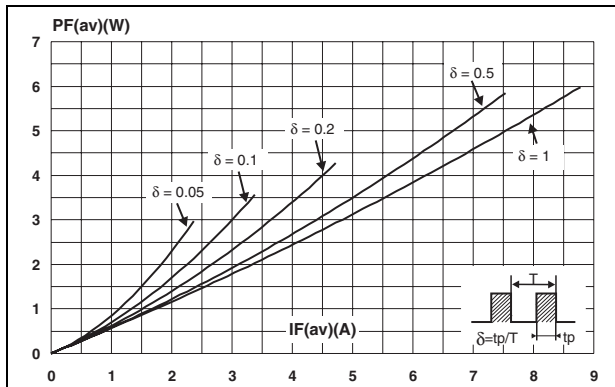


Figure 2. Average forward current  $(\delta = 0.5)$  versus ambient temperature

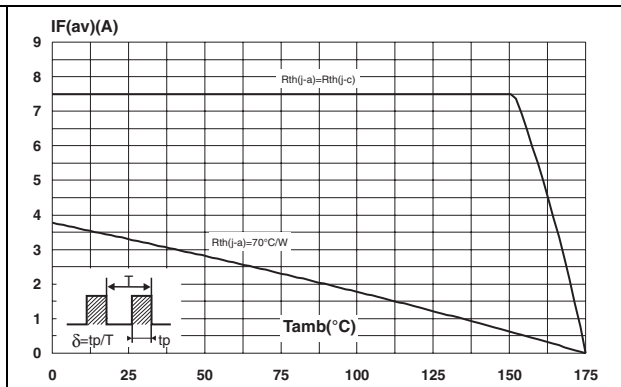


Figure 3. Normalized avalanche power derating versus pulse duration

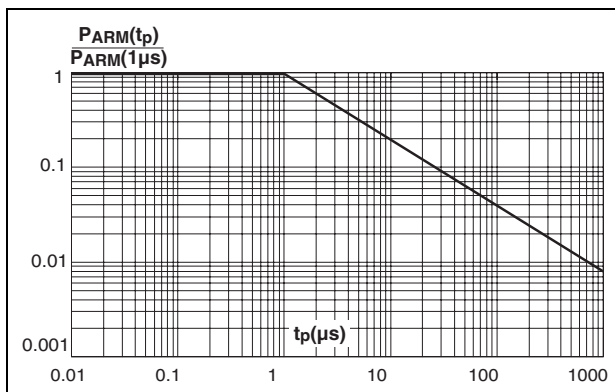


Figure 4. Normalized avalanche power derating versus junction temperature

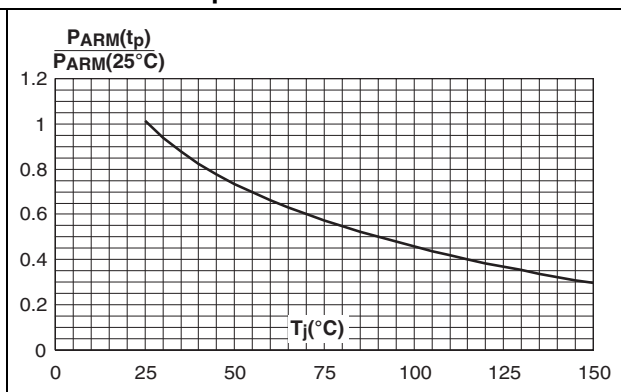


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values)

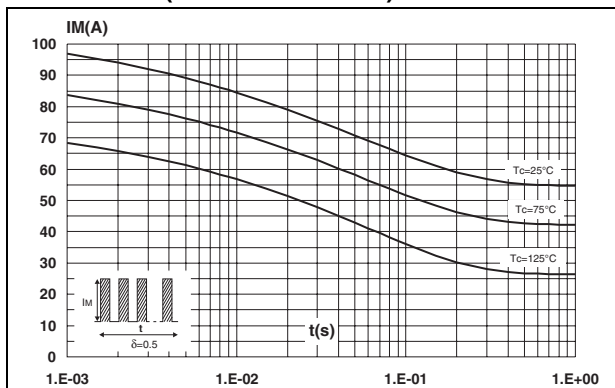
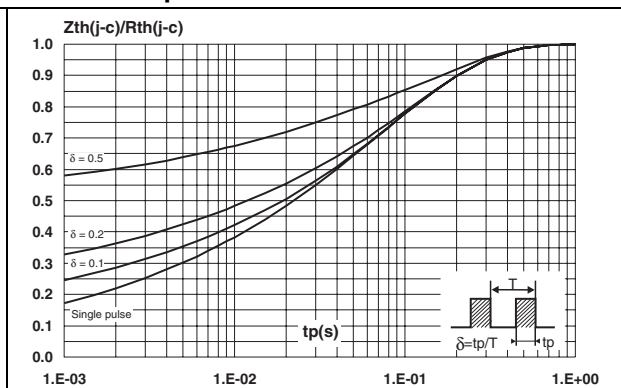
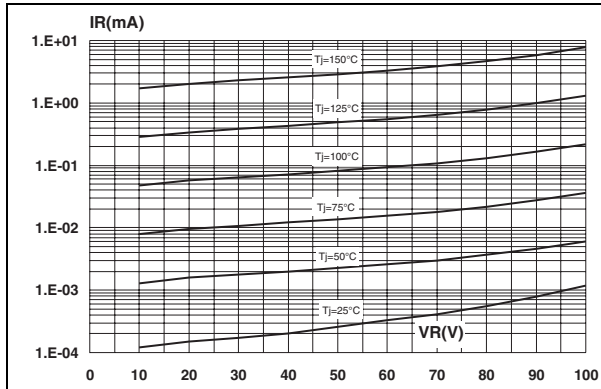


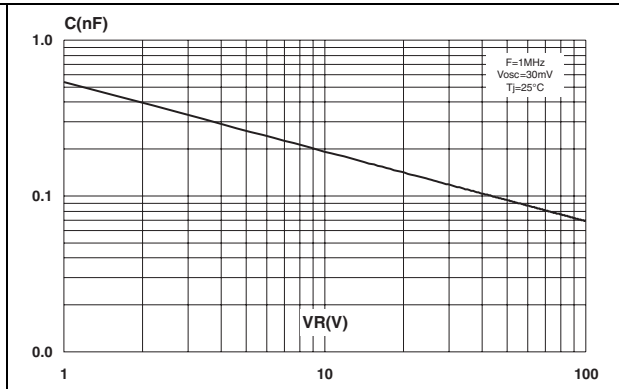
Figure 6. Relative variation of thermal impedance junction to case versus pulse duration



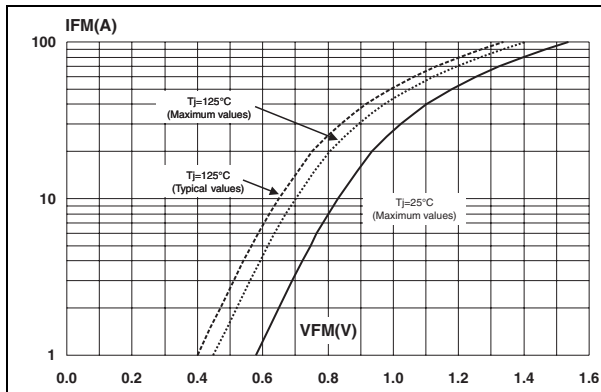
**Figure 7. Reverse leakage current versus reverse voltage applied (typical values)**



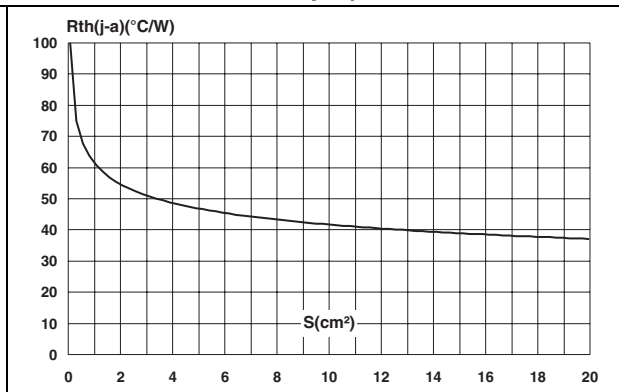
**Figure 8. Junction capacitance versus reverse voltage applied (typical values)**



**Figure 9. Forward voltage drop versus forward current**



**Figure 10. Thermal resistance junction to ambient versus copper surface under tab (epoxy printed board FR4, Cu: 35µm)**



## 2 Package Information

Epoxy meets UL94,V0

**Table 4. DPAK Package mechanical data**

Ref	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
C	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
H	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.031 typ.	
L4	0.60	1.00	0.023	0.039
V2	0°	8°	0°	8°

**Figure 11. DPAK Footprint (dimensions in mm)**

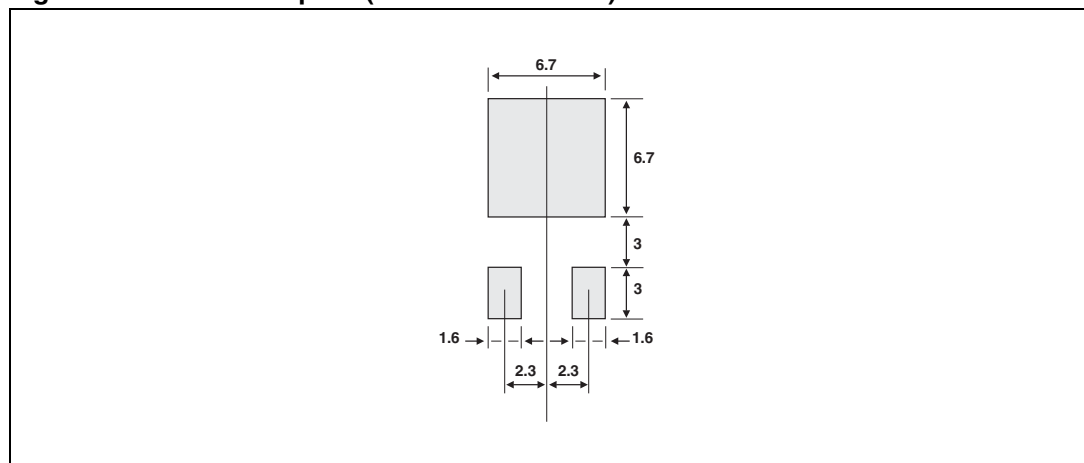
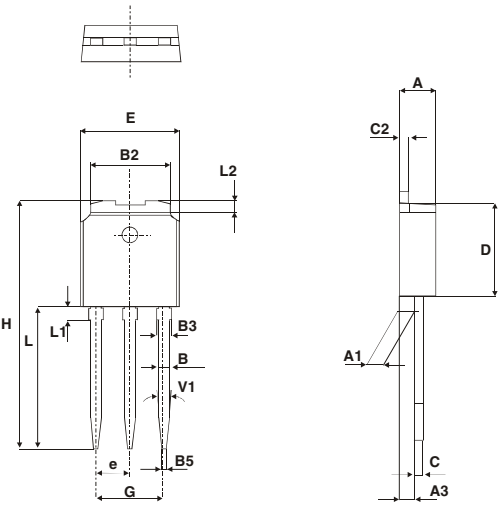


Table 5. IPAK Package mechanical data



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.20		2.40	0.086		0.094
A1	0.90		1.10	0.035		0.043
A3	0.70		1.30	0.027		0.051
B	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.212
B3			0.95			0.037
B5		0.30			0.035	
C	0.45		0.60	0.017		0.023
C2	0.48		0.60	0.019		0.023
D	6		6.20	0.236		0.244
E	6.40		6.60	0.252		0.260
e		2.28			0.090	
G	4.40		4.60	0.173		0.181
H		16.10			0.634	
L	9		9.40	0.354		0.370
L1	0.8		1.20	0.031		0.047
L2		0.80	1		0.031	0.039
V1		10°			10°	

### 3 Ordering Information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS15H100CB	S15H100	DPAK	0.30 g	75	Tube
STPS15H100CB-TR	S15H100	DPAK	0.30 g	2500	Tape and reel
STPS15H100CH	S15H100CH	IPAK	0.35 g	75	Tube

### 4 Revision History

Date	Revision	Changes
Mar-2004	3	Last issue
08-Jun-2006	4	Reformatted to current standard. Added IPAK.

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